

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
1	BRS	L1	94	257/\$.ccls. and (chip die ic) adj2 controller same (substrate board carrier)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/06/26 16:40	
2	BRS	L2	136	257/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/06/26 17:09	
3	BRS	L3	16	("5045921"   "5048664"   "5216278"   "5218378"   "5410124"   "5451721"   "5602422"   "5642265"   "5766021"   "5791552"   "5828128"   "5835355"   "5849130"   "6064576"   "6069407"   "6139972") .PN.	USPA T	2004/06/26 16:47	
4	BRS	L4	26	174/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPA T; US-P GPUB ; EPO; JPO; DERW ENT; IBM_ TDB	2004/06/26 16:52	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
5	BRS	L5	43	438/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:53	
6	BRS	L6	11	29/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (gap disconnect\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:54	
7	BRS	L10	2529	programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 16:59	
8	BRS	L11	184	257/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/26 17:04	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
9	BRS	L12	31	174/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:06	
10	BRS	L13	47	438/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:07	
11	BRS	L14	11	29/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:08	
12	BRS	L15	54	361/\$.ccls. and programmable adj2 (chip die ic substrate)	USPAT; US-PGPUB; ;EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:08	

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
13	BRS	L16	210	257/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:14	
14	BRS	L17	43	174/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:16	
15	BRS	L18	93	438/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:18	
16	BRS	L19	47	361/\$.ccls. and (chip die ic) same (substrate board carrier) same (wir\$3 adj pattern trace) with (space void)	USPAT; US-PGPUB ; EPO; JPO; DERWENT; IBM-TDB	2004/06/26 17:19	